

**Technical Data Sheet****0805 Package Chip LED****Preliminary****17-21-GPC-A0L1M2B0E-3T-AM**

香港至恩科技有限公司

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公司授权代理销售LITE-ON:光耦, 贴片LED灯等

进口原装, 现货供应, 价格优势, 技术支持

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**Feature**

- RoHS compliant.
- Chip LED package.
- Colorless diffused resin.
- Wide viewing angle 140°.
- Brightness: 11.20 to 28.00 mcd at 20 mA.
- Qualification according to AEC-Q101.
- Precondition: Bases on JEDEC J-STD 020 Level 3.
- Useable in severe lead free processes with automotive reflow profile (IR reflow or wave soldering))

This is a preliminary specification intended for design purposes and subject to change without prior notice.

**Applications**

- Automotive backlighting or indicator: Dashboard, switch, audio and video equipments...etc.
- Backlight: LCD, switches, symbol, mobile phone and illuminated advertising.
- Display for indoor and outdoor application.
- Ideal for coupling into light guides.
- Substitution of traditional light.
- Optical indicator.
- General applications.

**Device Selection Guide**

Chip	Emitted Color	Resin Color
Material		
AlGaInP	Pale Green	Water Clear

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**Preliminary****17-21-GPC-A0L1M2B0E-3T-AM****Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Rating	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I <sub>FP</sub>	60	mA
Power Dissipation	P <sub>d</sub>	60	mW
Junction Temperature	T <sub>j</sub>	115	°C
Operating Temperature	T <sub>opr</sub>	-40 ~ +100	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +110	°C
Thermal resistance	R <sub>th J-A</sub>	800	K/W
	R <sub>th J-S</sub>	450	K/W
Soldering Temperature	T <sub>sol</sub>	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	
ESD (Classification acc. AEC Q101)	ESD <sub>HBM</sub>	2000	V
	ESD <sub>MM</sub>	200	V

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**Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	$I_v$	11.20	-----	28.00	mcd	$I_F=20\text{mA}$
Viewing Angle	$2\theta_{1/2}$	-----	140	-----	deg	$I_F=20\text{mA}$
Peak Wavelength	$\lambda_p$	-----	561	-----	nm	$I_F=20\text{mA}$
Dominant Wavelength	$\lambda_d$	557.5	----	567.5	nm	$I_F=20\text{mA}$
Spectrum Radiation Bandwidth	$\Delta\lambda$	-----	20	-----	nm	$I_F=20\text{mA}$
Forward Voltage	$V_F$	1.75	----	2.35	V	$I_F=20\text{mA}$
Reverse Current	$I_R$	-----	-----	50	$\mu\text{A}$	$V_R=5\text{V}$
Temperature coefficient of $\lambda_p$	$TC_{\lambda_p}$	-----	0.13	-----	nm/K	$I_F=20\text{mA}$
Temperature coefficient of $\lambda_d$	$TC_{\lambda_d}$	-----	0.08	-----	nm/K	$I_F=20\text{mA}$
Temperature coefficient of $V_F$	$TC_V$	-----	-4.3	-----	mV/K	$I_F=20\text{mA}$

Note:

 Tolerance of Luminous Intensity:  $\pm 11\%$ 

 Tolerance of Dominant Wavelength:  $\pm 1\text{nm}$ 

 Tolerance of Forward Voltage:  $\pm 0.1\text{V}$

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**Preliminary****17-21-GPC-A0L1M2B0E-3T-AM****Bin Range of Luminous Intensity**

Bin Code	Min.	Max.	Unit	Condition
L1	11.20	14.00	mcd	I <sub>F</sub> =20mA
L2	14.00	18.00		
M1	18.00	22.40		
M2	22.40	28.00		

Note

Tolerance of Luminous Intensity : ±11%

**Bin Range of Dominant Wavelength**

Bin Code	Min.	Max.	Unit	Condition
C10	557.5	559.5	nm	I <sub>F</sub> =20mA
C11	559.5	561.5		
C12	561.5	563.5		
C13	563.5	565.5		
C14	565.5	567.5		

Note:

Tolerance of Dominant Wavelength: ±1nm

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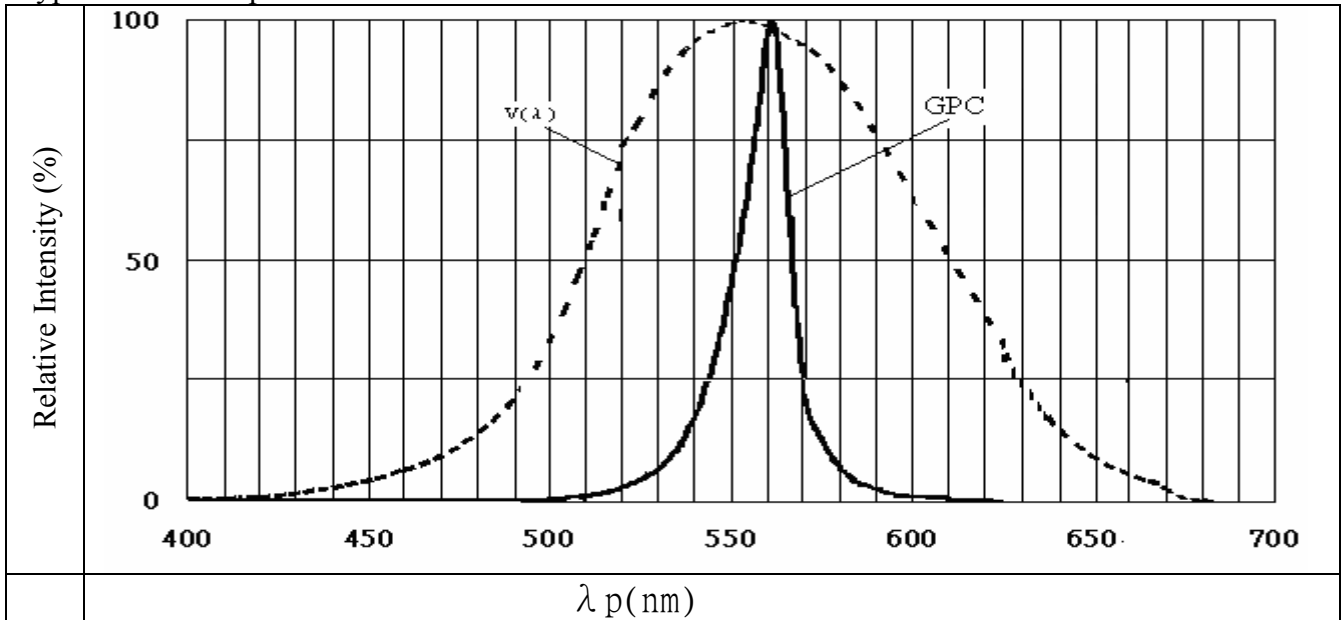
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**17-21-GPC-A0L1M2B0E-3T-AM**

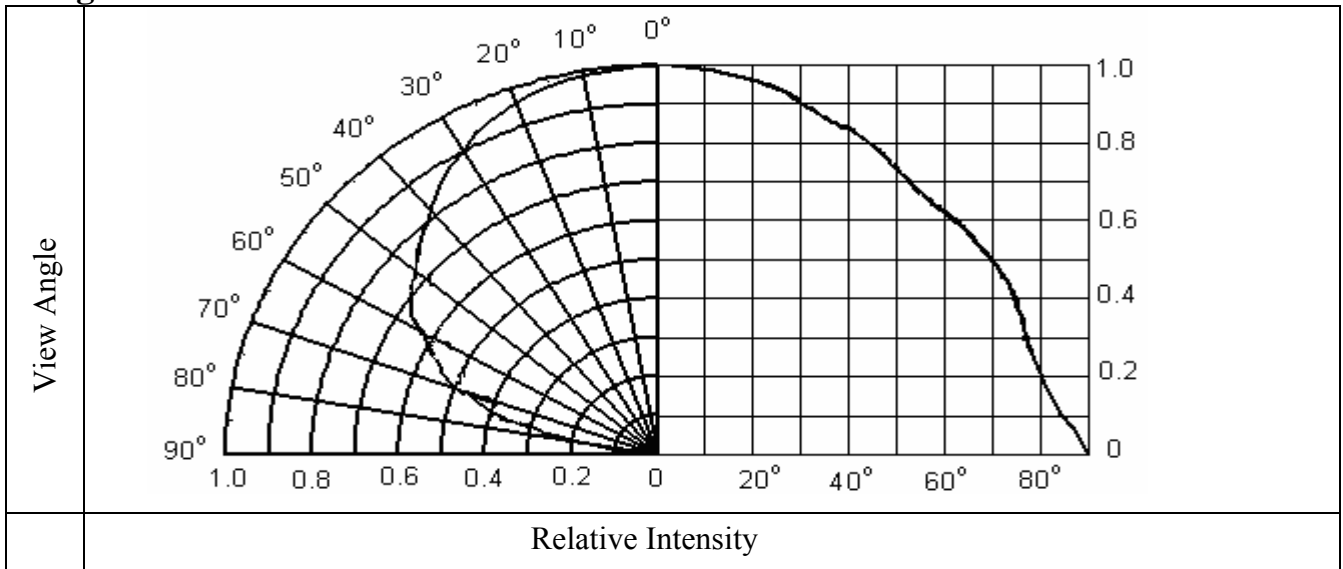
**Typical Electro-Optical Characteristics Curves**

Typical curve of spectral distribution:



Note:  $V(\lambda)$ =Standard eye response curve

**Diagram characteristics of radiation**



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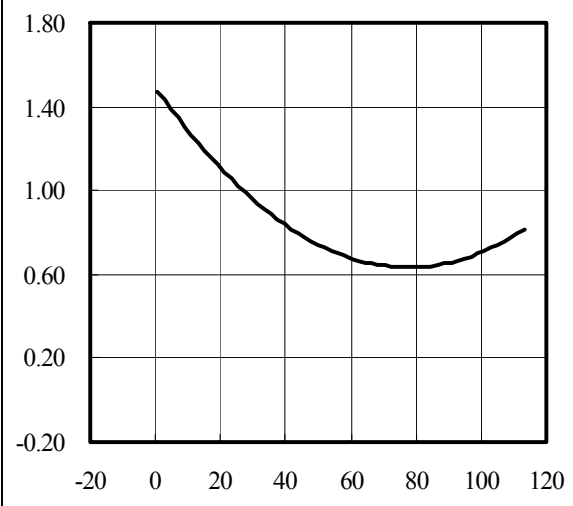
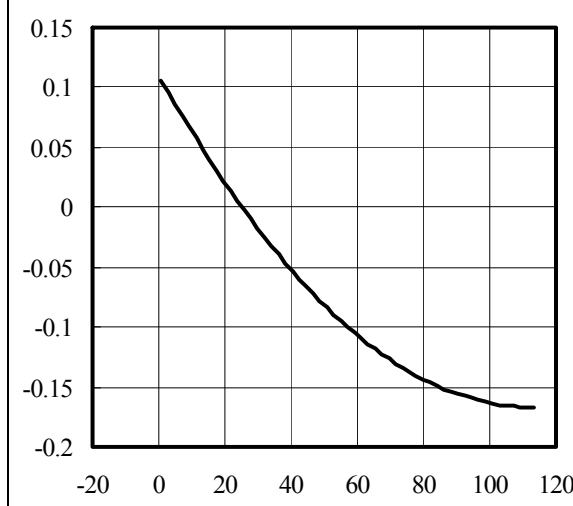
<b>Forward Current vs. Forward Voltage</b> (Ta=25°C)		<b>Dominant Wavelength vs. Forward Current</b> (Ta=25°C)	
Forward Current (mA)		Dominant Wavelength (nm)	
	Forward Voltage (V)		Forward Current (mA)
<b>Relative Luminous Intensity vs. Forward Current</b> (Ta=25°C)		<b>Forward current vs. Ambient and Solder Temperature</b>	
Relative Luminous Intensity		Forward Current (mA)	
	Forward Current (mA)		Temperature (°C)

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Relative Luminous Intensity vs. Junction Temperature		Relative Forward Voltage vs. Junction Temperature	
Relative Luminous Intensity		Relative Luminous Intensity	
Junction Temperature (°C)		Junction Temperature (°C)	
Note: $f(T_j) = I_v / I_v(25^\circ\text{C}); I_F = 20\text{mA}$		Note: $\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j); I_F = 20\text{mA}$	

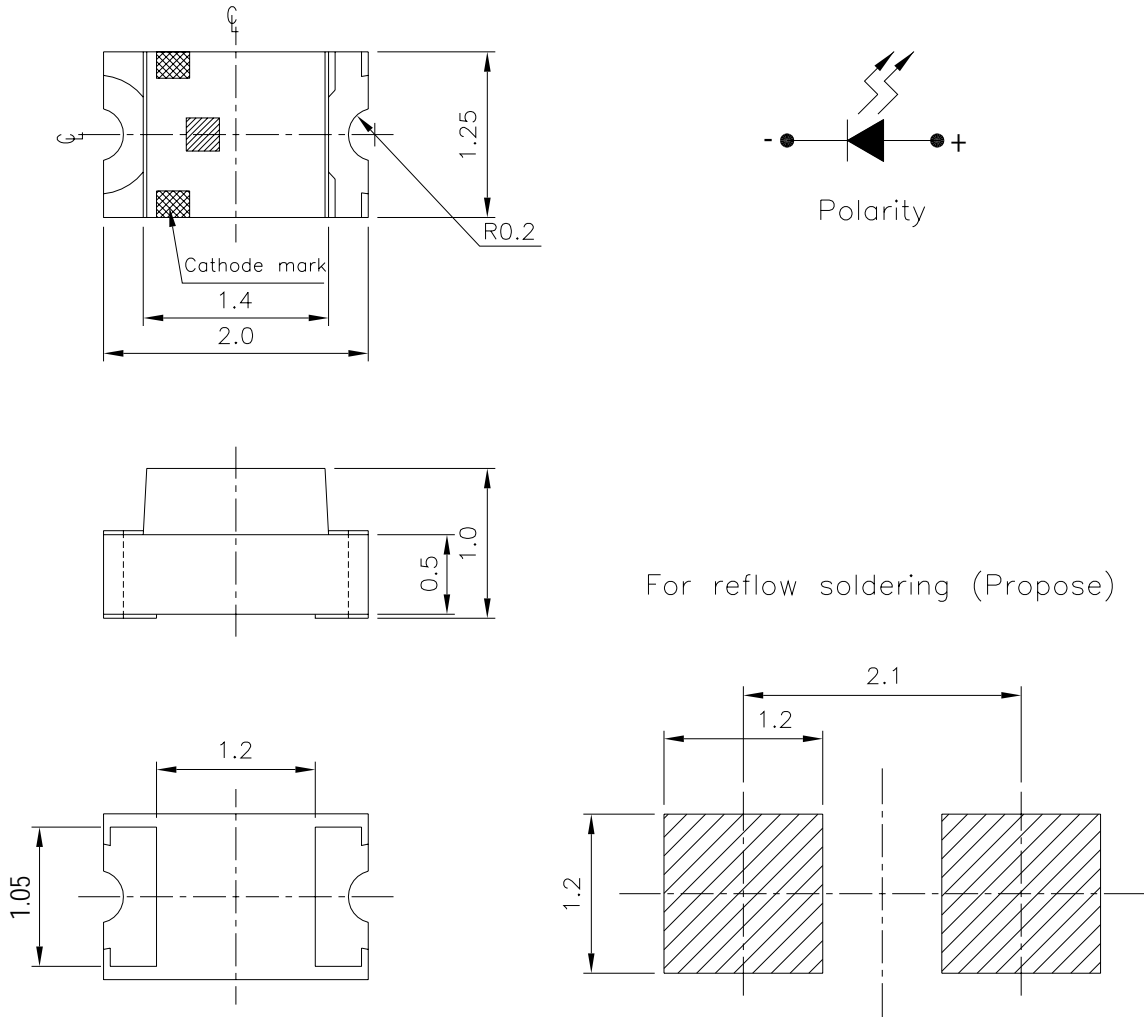
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Package Dimension



Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm



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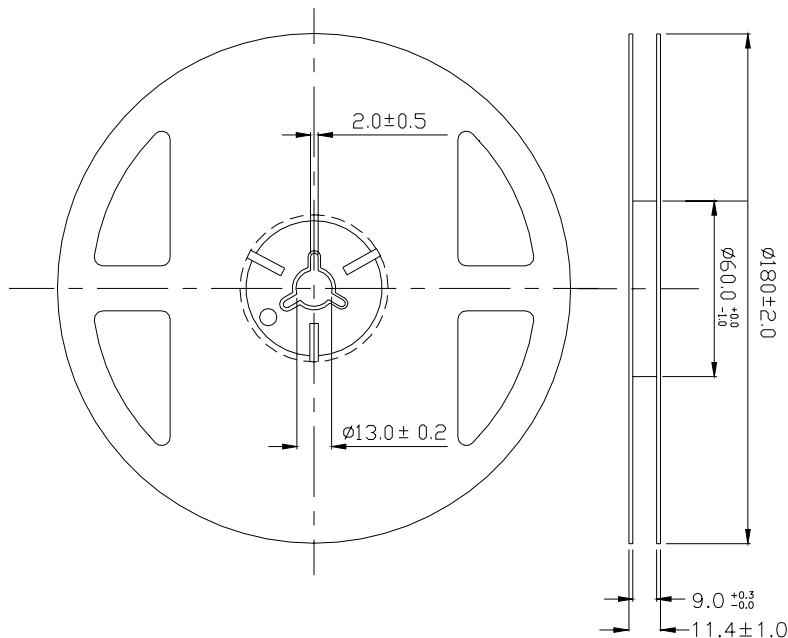
**17-21-GPC-A0L1M2B0E-3T-AM**

**Label Explanation**

- **CPN:** Customer's Product Number
- **P/N:** Product Number
- **QTY:** Packing Quantity
- **CAT:** Luminous Intensity Rank
- **HUE:** Dom. Wavelength Rank
- **REF:** Forward Voltage Rank
- **LOT No:** Lot Numbe



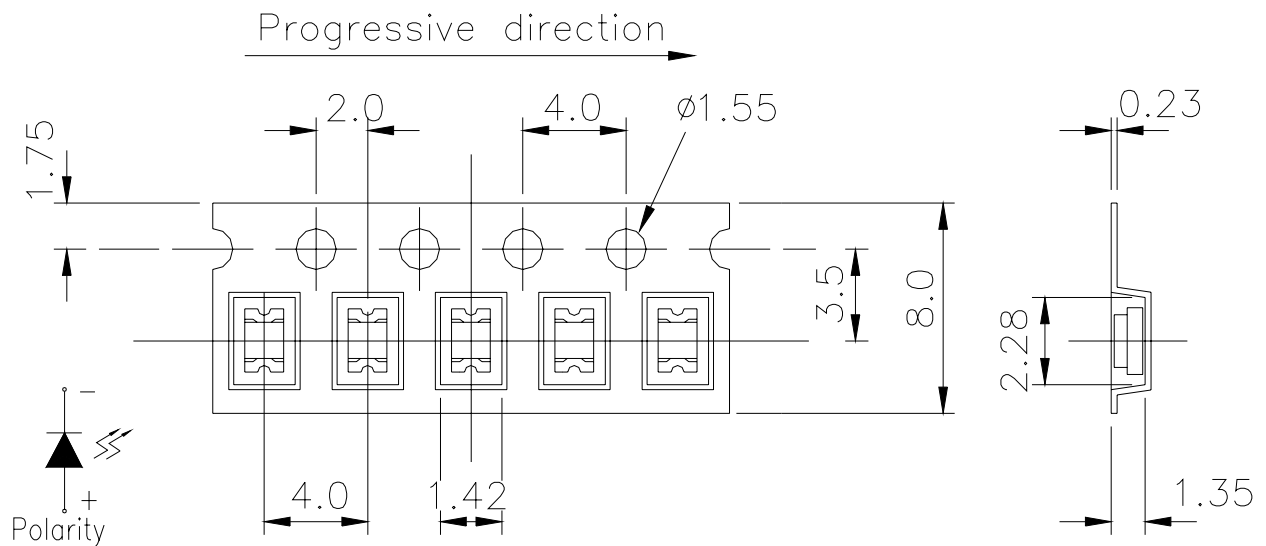
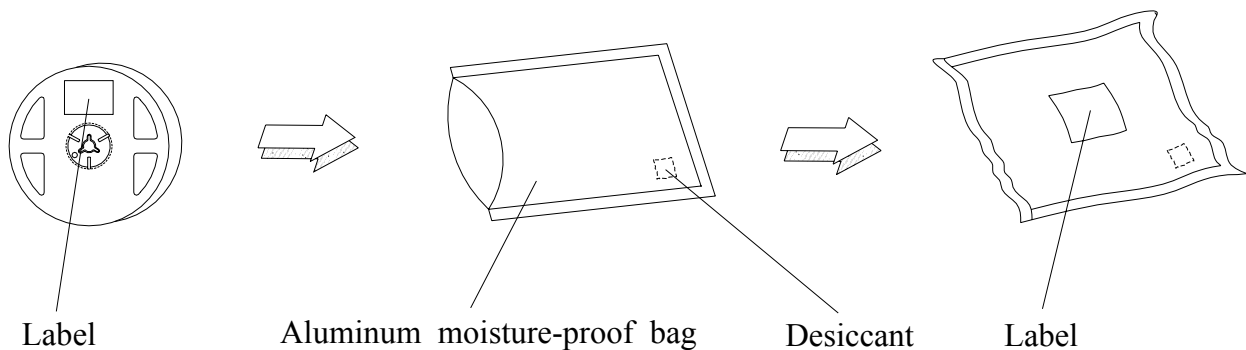
**Reel Dimensions**

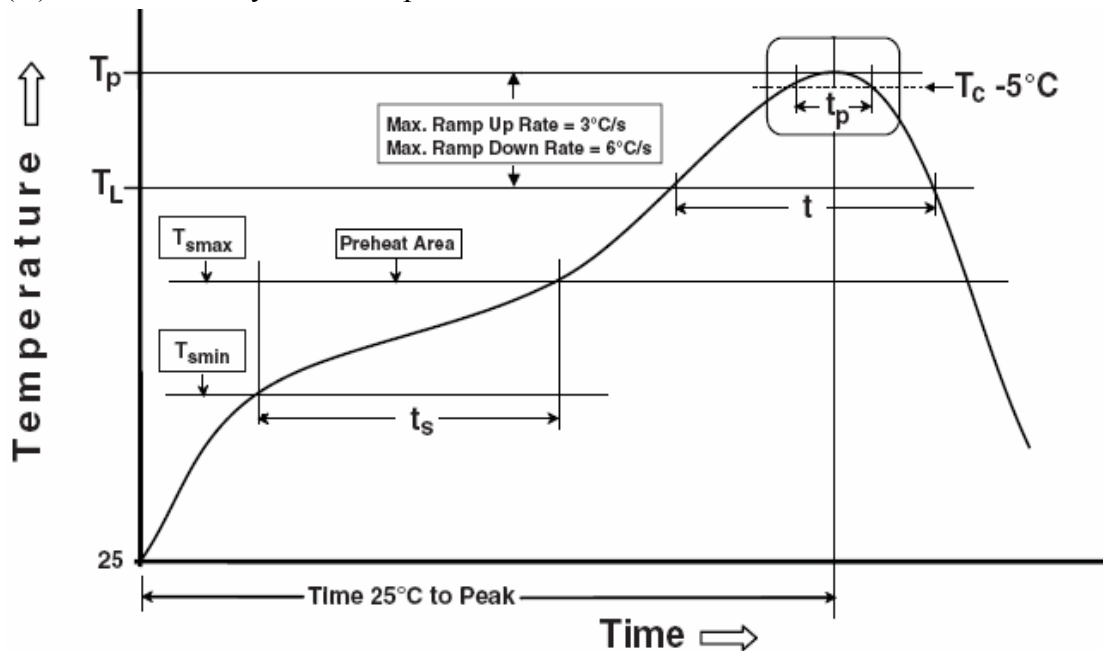


Note: Unit = mm

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**Preliminary****17-21-GPC-A0L1M2B0E-3T-AM****Carrier Tape Dimensions: Loaded Quantity 3000 pcs Per Reel**Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm**Moisture Resistant Packaging Process and Materials**

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**Precautions for Use**
**1. Soldering Condition**
**1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile**

**Note:**
**Preheat**

 Temperature min ( $T_{smin}$ )

 Temperature max ( $T_{smax}$ )

 Time ( $T_{smin}$  to  $T_{smax}$ ) ( $t_s$ )

 Average ramp-up rate ( $T_{smax}$  to  $T_p$ )

**Other**

 Liquidus Temperature ( $T_L$ )

 Time above Liquidus Temperature ( $t_L$ )

 Peak Temperature ( $T_p$ )

 Time within 5 °C of Actual Peak Temperature:  $T_p - 5^\circ\text{C}$ 

Ramp- Down Rate from Peak Temperature

Time 25°C to peak temperature

Reflow times

Reference: IPC/JEDEC J-STD-020D

150 °C

200°C

60-120 seconds

3 °C/second max.

217 °C

60-150 sec

260°C

30 s

6°C /second max.

8 minutes max.

3 times

All parameters are maximum body case temperature values and cannot be considered as a soldering profile. The body case temperature was measured by soldering a thermal couple to the soldering point of LEDs.

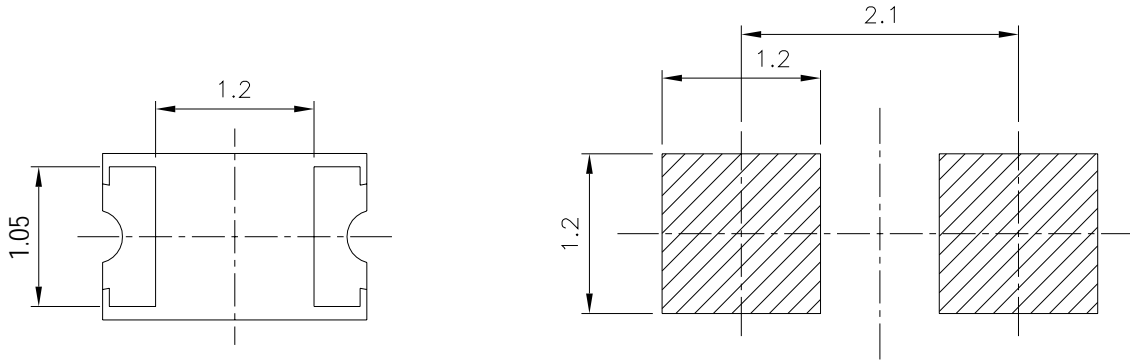
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(B) Recommend soldering pad



Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

3.1 Moisture proof bag should only be opened immediately prior to usage.

3.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.

3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.

3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350°C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.

**Application Restrictions**

1. High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.